

Specification sheet

General Feature

- *Application* Client PCs
- *Capacity* 1,000GB (1GB=1 Billion byte by IDEMA) * Actual usable capacity may be less (due to formatting, partitioning, operating system, applications or otherwise)
- *Form Factor* M.2 (2280)
- *Interface* PCIe Gen 3.0 x 4, NVMe 1.3
- *Dimension (WxHxD)* 80.15 x 22.15 x 2.38 (mm)
- *Weight* Max 8.0 g Weight
- *Storage Memory* Samsung V-NAND 3-bit MLC
- *Controller* Samsung Phoenix Controller
- *Cache Memory* Samsung 1GB Low Power DDR4 SDRAM

• *Special Feature*

- *TRIM Support* Supported
- *S.M.A.R.T Support* Supported
- *GC (Garbage Collection)* Auto Garbage Collection Algorithm
- *Encryption Support* AES 256-bit Encryption (Class 0)TCG/Opal IEEE1667 (Encrypted drive)
- *WWN Support* Not supported
- *Device Sleep Mode Support* Yes

• *Performance*

- *Sequential Read* Up to 3,500 MB/s * Performance may vary based on system hardware & configuration
- *Sequential Write* Up to 3,300 MB/s * Performance may vary based on system hardware & configuration
- *Random Read (4 KB, QD32)* Up to 600,000 IOPS * Performance may vary based on system hardware & configuration
- *Random Write (4KB, QD32)* Up to 550,000 IOPS * Performance may vary based on system hardware & configuration
- *Random Read (4 KB, QD1)* Up to 19,000 IOPS * Performance may vary based on system hardware & configuration
- *Random Write (4 KB, QD1)* Up to 60,000 IOPS * Performance may vary based on system hardware & configuration

• *Environment*

- *Average Power Consumption (system level)* * Average: 6 W * Maximum: 9 W (Burst mode) * Actual power consumption may vary depending on system hardware & configuration
- *Power consumption (Idle)* Max. 30 mW * Actual power consumption may vary depending on system hardware & configuration
- *Allowable Voltage* 3.3 V \pm 5 % Allowable voltage
- *Reliability (MTBF)* 1.5 Million Hours Reliability (MTBF)
- *Operating Temperature* 0 - 70 °C Operating Temperature
- *Shock* 1,500 G & 0.5 ms (Half sine)